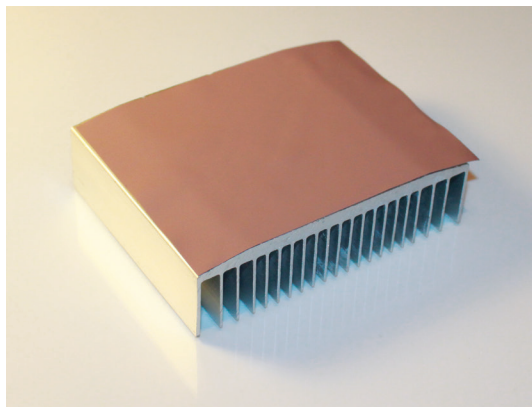


H48-2K

Thermal Conductive Pad



Features

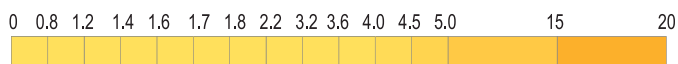
No carrier
Low contact thermal impedance
Non-Oil Bleed
High dielectric breakdown voltage

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Properties

Thermal Conductivity: 1.8 W/mK
(W/mK - Z Axis)



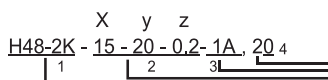
Hardness: 60 (Shore A)
(Shore A)



In the thermal resistance vs pressure vs deflection charts H48-2K provides low thermal impedance.
As the pressure increases the thermal impedance decreases. H48-2K provides good compliance and softness.

Property	H48-2K	Unit	Test Method
Thickness (+/- 10%)	0.1/0.2/0.3	mm	-
Colour	Dark Red	-	Visual
Construction	Silicone based with ceramic fillers (non-silicone oil)	-	-
Opt.Temp. Range	-45 to 200	°C	-
Density	2.1	g/cm ³	ASTM D792
Thermal Conductivity	1.8	W/mK	ASTM D5470
Hardness Shore A	60	-	ASTM D2240
Thermal Impedance			ASTM D5470
10psi	0.21/0.37/0.57	K- in ² /W	-
50psi	0.20/0.33/0.51	K- in ² /W	-
100psi	0.17/0.31/0.46	K- in ² /W	-
Percent Deflection			ASTM D575
10psi	2	%	-
50psi	5	%	-
100psi	11	%	-
Breakdown Voltage	1.2 / 2.5 / 3.5	kV	ASTM D149
TML	< 0.5%	%	ASTM E595
Tensile Strength	200	Psi	ASTM D412
Elongation	50	%	ASTM D412
Flammability Rating	V-0	-	UL 94

Available with an adhesive backing



1. Part Number
2. Size X-Y-Z
3. Adhesive backing - 0=None, 1A=one side, 2A=two sides
4. Quantity